

SCLS394J-APRIL 1999-REVISED FEBRUARY 2015

# SNx4LV132A Quadruple Positive-NAND Gates With Schmitt-Trigger Inputs

Technical

Documents

Sample &

Buv

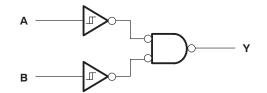
## 1 Features

- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 9 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot) >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 250 mA per JESD 17
- I<sub>off</sub> Supports Live Insertion, Partial Power-Down Mode, and Back Drive Protection
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## 2 Applications

- Industrial PC: Rugged PC and Laptop
- Access Control and Security: Camera Surveillance IP Network
- Vending, Payment and Change Machines
- Patient Monitoring STB / DVR / Streaming Media (Withdraw)
- Other Motor Drives (Such as Switch Reluctance)

## 4 Logic Diagram (Positive Logic)



## 3 Description

Tools &

Software

The 'LV132A devices are quadruple positive-NAND gates designed for 2-V to 5.5-V  $V_{CC}$  operation.

Support &

Community

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The <u>'LV132A</u> devices perform the Boolean function Y =  $\overline{A \cdot B}$  or Y =  $\overline{A + B}$  in positive logic.

Each circuit functions as a NAND gate, but because of the Schmitt trigger, it has different input threshold levels for positive- and negative-going signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean jitter-free output signals.

Device information.							
PART NUMBER	PACKAGE	BODY SIZE (NOM)					
	SOIC (14)	8.65 mm × 3.91 mm					
	SOP (14)	10.30 mm × 5.30 mm					
LV132A	SSOP (14)	6.20 mm × 5.30 mm					
	TSSOP (14)	5.00 mm × 4.40 mm					
	TVSOP (14)	3.60 mm × 4.40 mm					

Device Information<sup>(1)</sup>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

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## 5 Revision History

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•	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation
	section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and
	Mechanical, Packaging, and Orderable Information section
	Induced encrypting free circlementatives mayimum from 95% to 135% for SNTAL V(136A

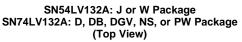
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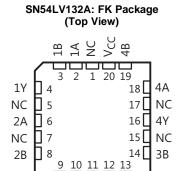
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## 6 Pin Configuration and Functions



1A [	1	U	14	] v <sub>cc</sub>
1B [	2		13	<b>4</b> B
1Y 🛛	3		12	] 4A
2A 🛛	4		11	] 4Y
2В	5		10	<b>3</b> B
2Y 🛛	6		9	3A
gnd [	7		8	] 3Y



2Y GND NC 3Y 3A

A. NC - No internal connection

#### Pin Functions

PIN		1/0	DESCRIPTION
NO.	NAME	I/O	DESCRIPTION
1	1A	I	1A input
2	1B	I	1B
3	1Y	0	1Y
4	2A	I	2A
5	2B	I	2B
6	2Y	0	2Y
7	GND	_	GND
8	3Y	0	3Y
9	3A	I	3A
10	3B	I	3B
11	4Y	0	4Y
12	4A	I	4A
13	4B	I	4B
14	V <sub>CC</sub>	_	V <sub>cc</sub>

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## 7 Specifications

## 7.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		-0.5	7	V
VI	Input voltage <sup>(2)</sup>		-0.5	7	V
Vo	Voltage applied to any output in the h	igh-impedance or power-off state <sup>(2)</sup>	-0.5	7	V
Vo	Output voltage <sup>(2) (3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current	$V_{O} = 0$ to $V_{CC}$	-25	25	mA
	Continuous current through V <sub>CC</sub> or GND		-50	50	mA
T <sub>stg</sub>	Storage temperature		-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value is limited to 5.5-V maximum.

## 7.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	V
	aloonargo	Machine model (A115-A)	200	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

## 7.3 Recommended Operating Conditions

See (1)(2)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		$V_{CC} = 2 V$		-50	μA
I <sub>OH</sub>	High lovel output ourrent	$V_{CC}$ = 2.3 V to 2.7 V		-2	
	High-level output current	$V_{CC} = 3 V$ to 3.6 V		-6	mA
		$V_{CC}$ = 4.5 V to 5.5 V		-12	
		$V_{CC} = 2 V$		50	μA
	Low lovel output ourrent	$V_{CC}$ = 2.3 V to 2.7 V		2	
I <sub>OL</sub>	Low-level output current	$V_{CC} = 3 V$ to 3.6 V		6	mA
		$V_{CC}$ = 4.5 V to 5.5 V		12	
-	Operating free air temperature	SN54LV132A	-55	125	°C
T <sub>A</sub>	Operating free-air temperature	SN74LV132A	-40	125	

 All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See the TI application report, Implications of Slow or Floating CMOS Inputs, SCBA004.

(2) SN54LV132A is in product preview



## 7.4 Thermal Information

over operating free-air temperature range (unless otherwise noted)

	THERMAL METRIC <sup>(1)</sup>	D	DB	DGV	NS	PW	
			14 PINS				
$R_{\theta JA}$	Junction-to-ambient thermal resistance	90.6	107.1	129.0	90.7	122.6	
R <sub>0JC(top)</sub>	Junction-to-case (top) thermal resistance	50.9	59.6	52.1	48.3	51.4	
$R_{\theta J B}$	Junction-to-board thermal resistance	44.8	54.4	62.0	49.4	64.4	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	14.7	20.5	6.5	14.6	6.7	
$\Psi_{JB}$	Junction-to-board characterization parameter	44.5	53.8	61.3	49.1	63.8	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

				SN54L	.V132A <sup>(1)</sup>	SN74		
PARAMETER		TEST CONDITIONS	V <sub>cc</sub>	MIN	ΤΥΡ ΜΑΧ	MIN	ΤΥΡ ΜΑΧ	UNIT
			2.5 V	1	1.75	1	1.75	
$V_{T+}$	Positive-going input threshold voltage		3.3 V	1.31	2.31	1.31	2.31	V
	threahold voltage		5 V	1.95	3.5	1.95	3.5	
			2.5 V	0.75	1.5	0.75	1.5	
V <sub>T-</sub> Negative-going input threshold voltage		3.3 V	0.99	2.07	0.99	2.07	V	
	anoonola voltago		5 V	1.5	3.05	1.5	3.05	
			2.5 V	0.25	1	0.25	1	
$\Delta V_{\rm T}$	Hysteresis (V <sub>T+</sub> – V <sub>T-</sub> )		3.3 V	0.33	1.32	0.33	1.32	V
	(v <sub>T+</sub> - v <sub>T</sub> -)		5 V	0.5	2	0.5	2	
		I <sub>OH</sub> = -50 μA	2 to 5.5 V	V <sub>CC</sub> – 0.1		V <sub>CC</sub> – 0.1		
.,		$I_{OH} = -2 \text{ mA}$	2.3 V	2		2		V
V <sub>OH</sub>		$I_{OH} = -6 \text{ mA}$	3 V	2.48		2.48		
		I <sub>OH</sub> = -12 mA	4.5 V	3.8		3.8		
		I <sub>OL</sub> = 50 μA	2 to 5.5 V		0.1		0.1	
V		$I_{OL} = 2 \text{ mA}$	2.3 V		0.4		0.4	v
V <sub>OL</sub>		$I_{OL} = 6 \text{ mA}$	3 V		0.44		0.44	v
		I <sub>OL</sub> = 12 mA	4.5 V		0.55		0.55	
կ		$V_I = 5.5 V \text{ or GND}$	0 to 5.5 V		±1		±1	μA
Icc		$V_{I} = V_{CC} \text{ or GND}, I_{O} = 0$	5.5 V		20		20	μA
I <sub>off</sub>		$V_{I}$ or $V_{O}$ = 0 to 5.5 V	0 V		5		5	μA
Ci		$V_I = V_{CC}$ or GND	3.3 V		1.9		1.9	pF

(1) SN54LV132A is in product preview

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#### 7.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 2.5 V ±0.2 V (unless otherwise noted) (see Figure 3)

	DADAMETED			LOAD	т	<sub>A</sub> = 25°C		SN54LV	132A <sup>(1)</sup>	SN74LV	/132A	UNIT
PARAMETER	FROM (INPUT)	TO (OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
		A or B	V	C <sub>L</sub> = 15 pF		7.9 <sup>(2)</sup>	16.5 <sup>(2)</sup>	1 <sup>(2)</sup>	18.5 <sup>(2)</sup>	1	18.5	20
	<sup>L</sup> pd		T	C <sub>L</sub> = 50 pF		10.8	20.2	1	23	1	23	ns

(1) SN54LV132A is in product preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.7 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ±0.3 V (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD	т	<sub>A</sub> = 25°C		SN54LV1	132A <sup>(1)</sup>	SN74LV	/132A	UNIT
		10 (001201)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A or P	×	C <sub>L</sub> = 15 pF		5.6 <sup>(2)</sup>	11.9 <sup>(2)</sup>	1 <sup>(2)</sup>	14 <sup>(2)</sup>	1	14	2
lpd	A or B	ř	C <sub>L</sub> = 50 pF		7.6	15.4	1	17.5	1	17.5	ns

(1) SN54LV132A is in product preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.8 Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC} = 5 V \pm 0.5 V$  (unless otherwise noted) (see Figure 3)

PARAMETER	FROM	то	LOAD	т	<sub>A</sub> = 25°C		SN54LV	132A <sup>(1)</sup>	SN74LV	132A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	
	A or B	V	C <sub>L</sub> = 15 pF		3.9 <sup>(2)</sup>	7.7 <sup>(2)</sup>	1 <sup>(2)</sup>	9(2)	1	9	20
lpd	AUB	T	C <sub>L</sub> = 50 pF		5.3	9.7	1	11	1	11	ns

(1) SN54LV132A is in product preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

## 7.9 Noise Characteristics for SN74LV132A

 $V_{CC}$  = 3.3 V,  $C_{L}$  = 50 pF,  $T_{A}$  = 25°C<sup>(1)</sup>

	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.21	0.8	
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.09	-0.8	
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		3.12		V
V <sub>IH(D)</sub>	High-level dynamic input voltage	2.31			
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.99	

(1) Characteristics are for surface-mount packages only.

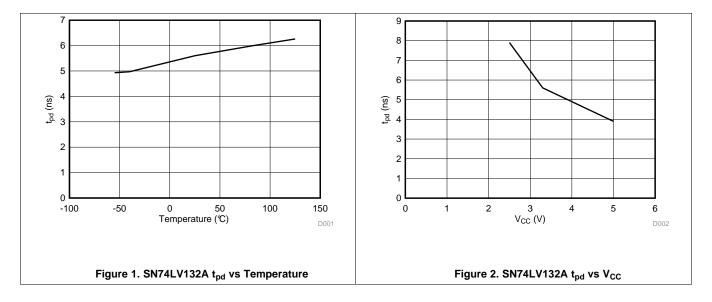
## 7.10 Operating Characteristics

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	TYP	UNIT	
<u> </u>	Dawar dissinction consoltance		3.3 V	7.5	~ [	
C <sub>pd</sub>	Power dissipation capacitance	C <sub>L</sub> = 50 pF, f = 10 MHz	5 V	11.2	рF	



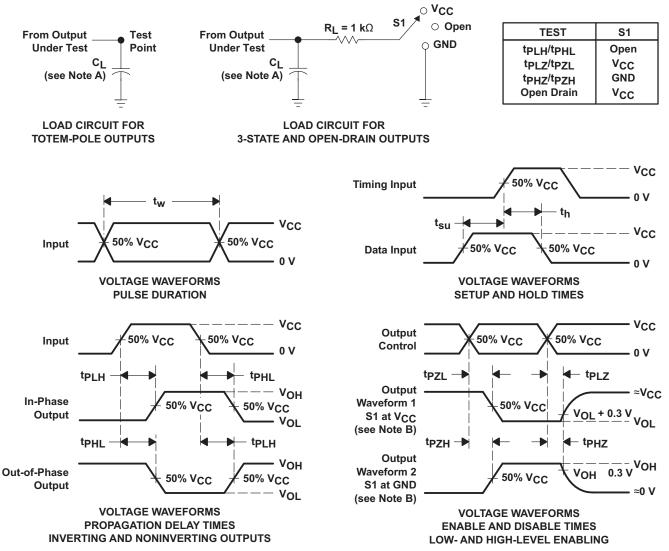
## 7.11 Typical Characteristics



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## 8 Parameter Measurement Information



- A. C<sub>L</sub> includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and tPZH are the same as t<sub>en</sub>.
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

#### Figure 3. Load Circuit and Voltage Waveforms



### 9 Detailed Description

#### 9.1 Overview

The SN74LV132A Is a quadruple 2-input positive NAND gate with low drive that produces slow rise and fall times. This reduces ringing on the output signal. Each circuit functions as a NAND gate, but because of the Schmitt trigger, it has different input threshold levels for positive- and negative-going signals. These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean jitter-free output signals.

#### 9.2 Functional Block Diagram

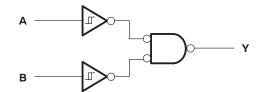


Figure 4. Logic Diagram (Positive Logic)

#### 9.3 Feature Description

- Wide operating voltage range, operates from 2 to 5.5 V
- Allows down voltage translation, inputs accept voltages to 5.5 V

#### 9.4 Device Functional Modes

#### Table 1. Function Table

INP	OUTPUT	
Α	В	Y
Н	Н	L
L	Х	Н
Х	L	Н



## **10** Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### **10.1** Application Information

The SN74LV132A is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs can accept voltages to 5.5 V at any valid  $V_{CC}$  making it Ideal for down translation.

#### **10.2 Typical Application**

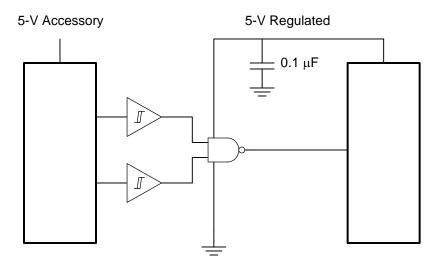


Figure 5. Typical Application Schematic

#### 10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing. The Schmitt trigger inputs allow for slow or noisy inputs while producing clean outputs.

#### 10.2.2 Detailed Design Procedure

- 1. Recommended input conditions
  - Specified high and low levels. See (V<sub>IH</sub> and V<sub>IL</sub>) in *Recommended Operating Conditions*.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V<sub>CC</sub>
- 2. Recommend output conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part
  - Outputs should not be pulled above V<sub>CC</sub>



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## **Typical Application (continued)**

#### 10.2.3 Application Curve

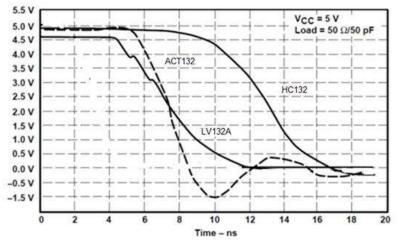


Figure 6. Switching Characteristics Comparison

## **11 Power Supply Recommendations**

The power supply can be any voltage between the min and max supply voltage rating located in *Recommended Operating Conditions*.

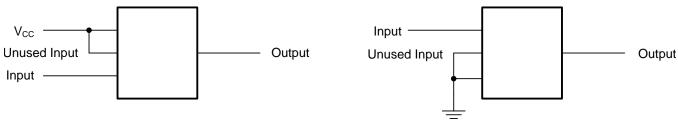
Each V<sub>CC</sub> terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1  $\mu$ F and if there are multiple V<sub>CC</sub> terminals then TI recommends .01  $\mu$ F or .022  $\mu$ F for each power terminal. It is okay to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu$ F and 1  $\mu$ F are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 12 Layout

#### 12.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float. In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$  whichever make more sense or is more convenient. It is generally okay to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the IOs so they also cannot float when disabled.

#### 12.2 Layout Example



#### Figure 7. Layout Recommendation

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## **13 Device and Documentation Support**

## 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54LV132A	Click here	Click here	Click here	Click here	Click here
SN74LV132A	Click here	Click here	Click here	Click here	Click here

#### Table 2. Related Links

## 13.2 Trademarks

All trademarks are the property of their respective owners.

## 13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 13.4 Glossary

#### SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: SN54LV132A SN74LV132A





## PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty		Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drailing		<u> </u>	(2)	(6)	(3)		(4/5)	
SN74LV132ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	Samples
SN74LV132ADGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	Samples
SN74LV132ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	Samples
SN74LV132ADRE4	LIFEBUY	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	
SN74LV132ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV132A	Samples
SN74LV132APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	Samples
SN74LV132APWRG4	LIFEBUY	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV132A	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



2-Nov-2023

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Texas

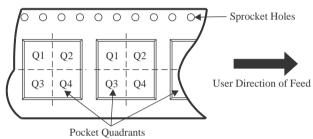
STRUMENTS

### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



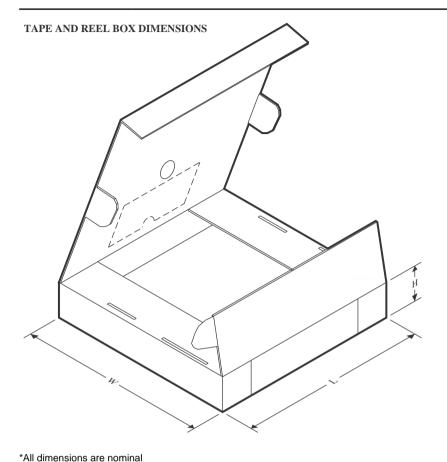
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV132ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV132ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV132ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV132ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV132APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV132APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

Pack Materials-Page 1



# PACKAGE MATERIALS INFORMATION

8-Dec-2023



Device	Package Type	vpe Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV132ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LV132ADGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74LV132ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LV132ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN74LV132APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV132APWR	TSSOP	PW	14	2000	356.0	356.0	35.0

Pack Materials-Page 2

## MECHANICAL DATA

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 7,40 5,00 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 0,15 0,05 Seating Plane - 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



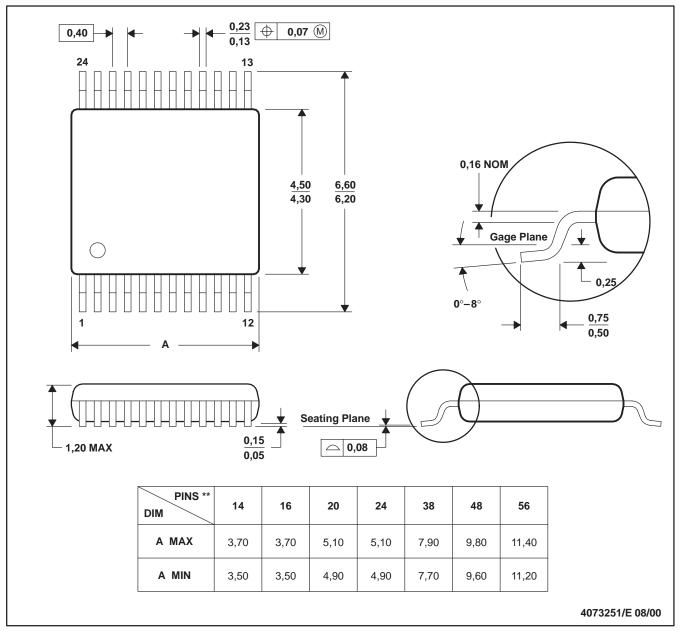
## **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

## DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

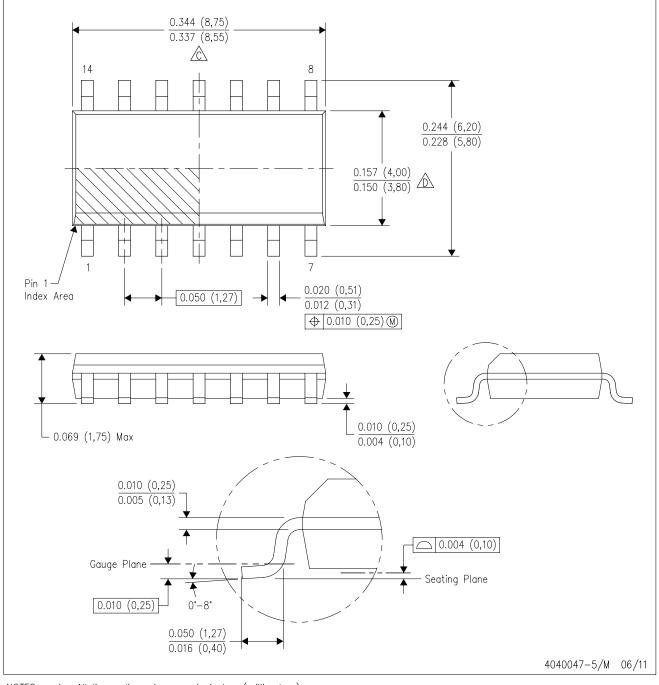
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

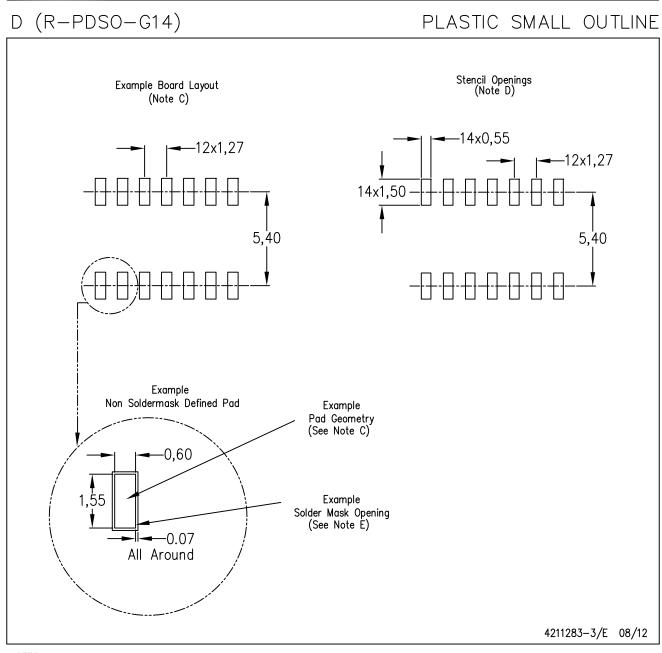
PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





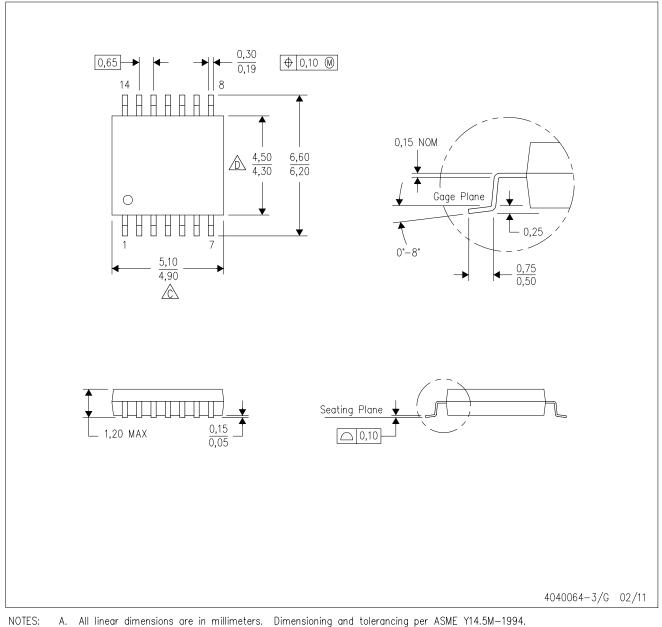
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
   E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



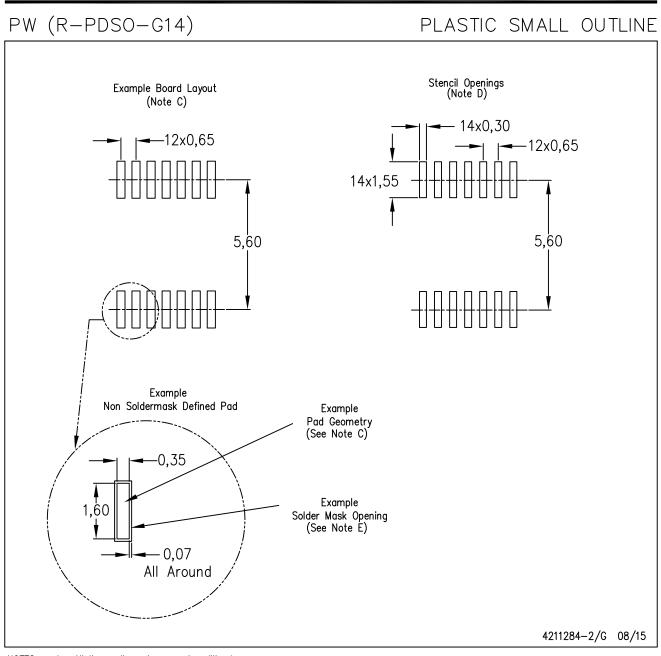
B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



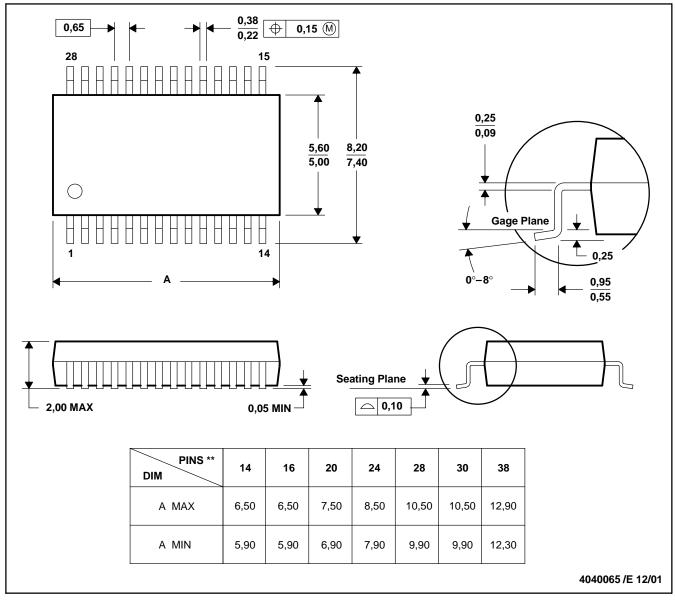
## **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

## DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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